

# SOT702-1

plastic, very thin fine-pitch ball grid array package; 56 balls;  
0.65 mm pitch; 4.5 mm x 7 mm x 0.65 mm body

30 January 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	VFBGA56
<b>Package type industry code</b>	VFBGA56
<b>Package style descriptive code</b>	VFBGA (very thin fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-225
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-7-2003
<b>Manufacturer package code</b>	SOT702

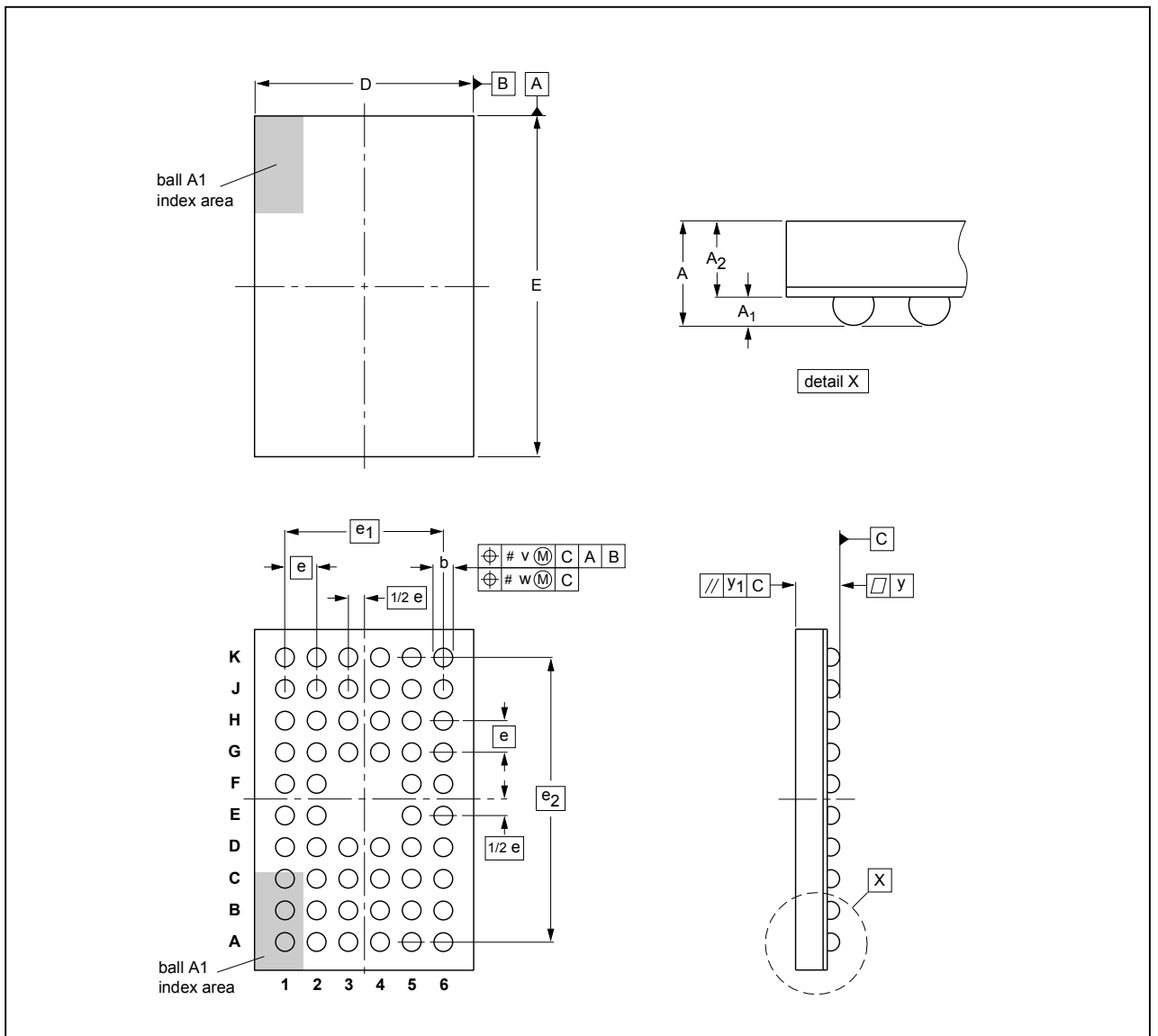
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	7	4.6	mm
E	package width	6.9	-	4.5	7.1	mm
A	seated height	-	-	1	1	mm
A <sub>2</sub>	package height	0.6	-	0.65	0.7	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	56	-	

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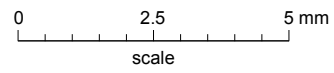
## 2. Package outline

VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 x 7 x 0.65 mm SOT702-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1	0.3 0.2	0.7 0.6	0.45 0.35	4.6 4.4	7.1 6.9	0.65	3.25	5.85	0.15	0.08	0.08	0.1



OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT702-1		MO-225				-02-08-08 03-07-01

Fig. 1. Package outline VFBGA56 (SOT702-1)

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### 3. Soldering

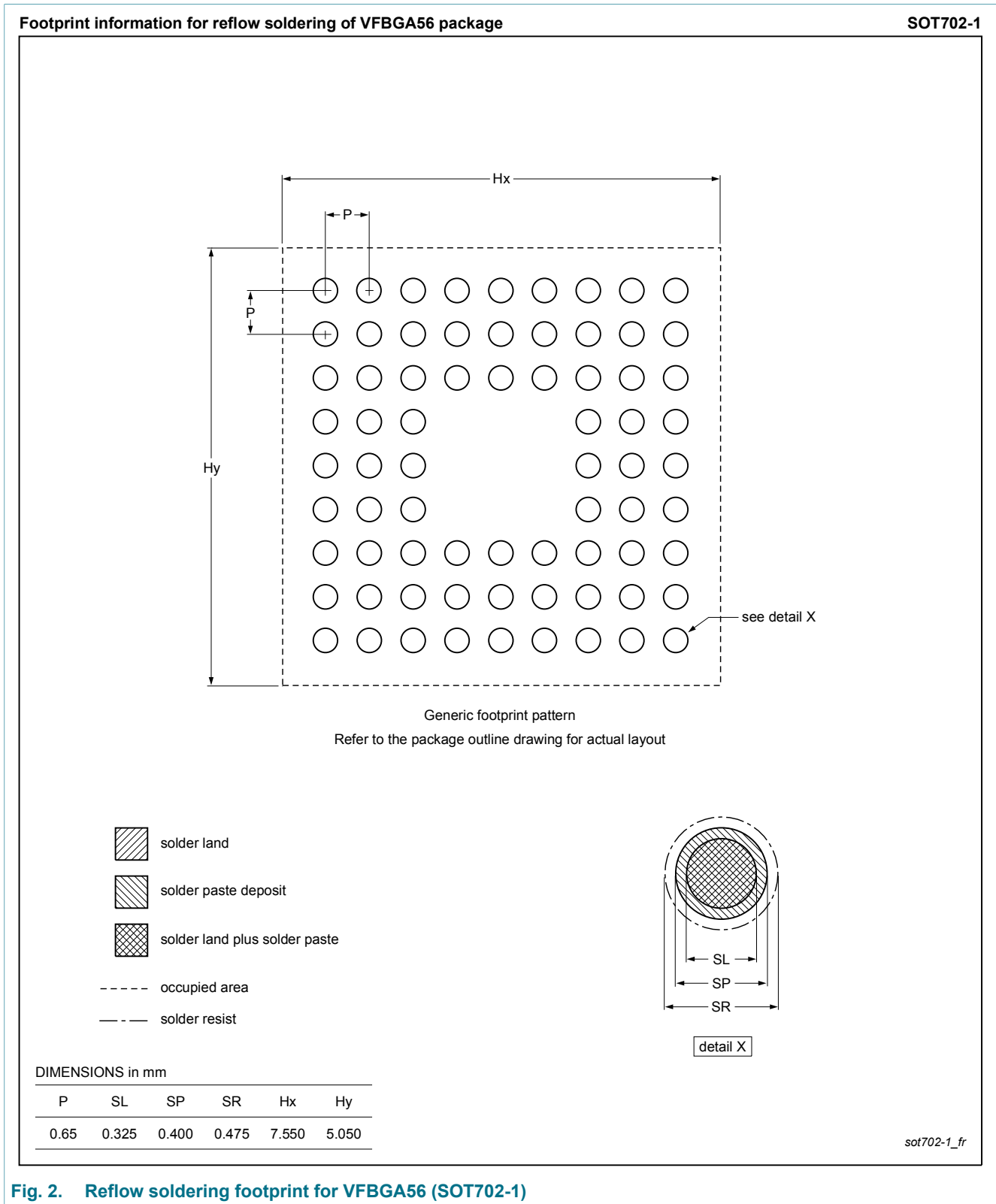


Fig. 2. Reflow soldering footprint for VFPGA56 (SOT702-1)

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plastic, very thin fine-pitch ball grid array package; 56 balls; 0.65 mm pitch; 4.5 mm x 7 mm x 0.65 mm  
body

## 4. Legal information

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